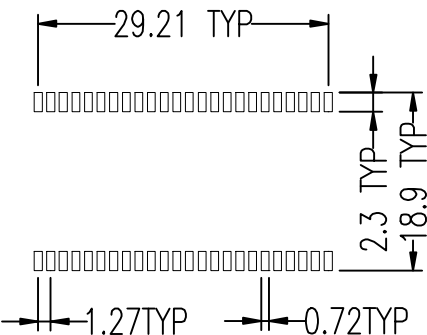
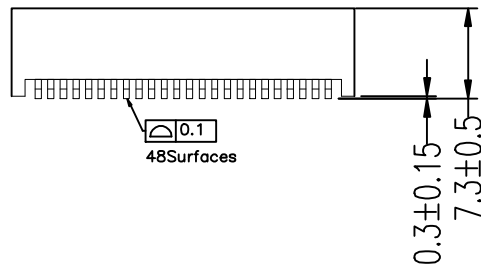
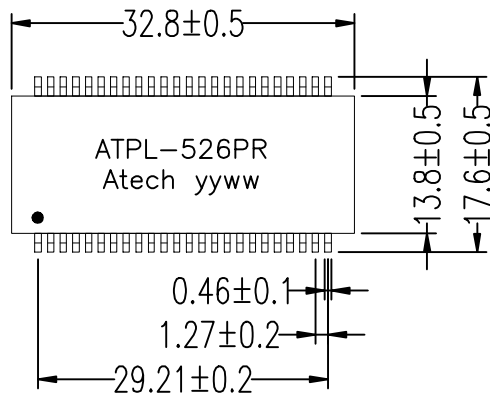
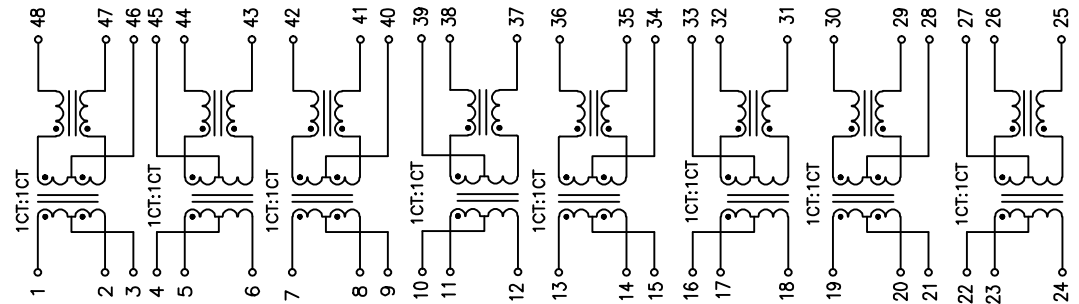




SUGGESTED PAD LAYOUT

UNLESS OTHERWISE SPECIFIED ALL TOLERANCES ARE XX.XX±0.25 0.XX±0.05

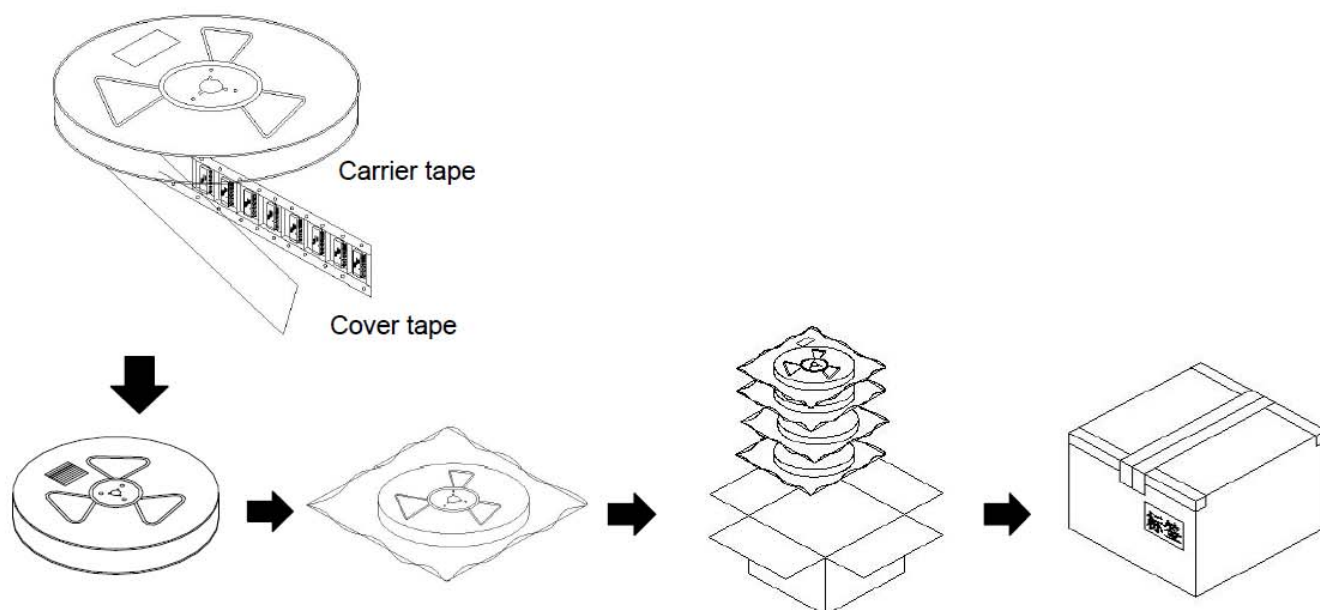
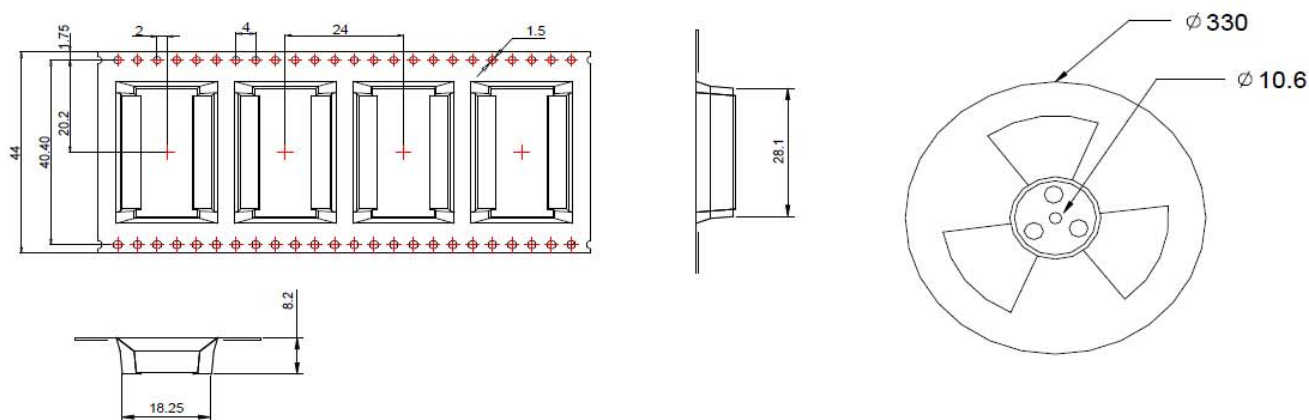


ELECTRICAL CHARACTERISTICS @25°C :

1. INSULATION HI-POT(PRI./SEC.) : 1500Vrms, 1mA, 60SEC
2. TURN RATIO (±5%) : TX = 1CT : 1CT , RX = 1CT : 1CT
3. OCL : 350uH MIN. @100kHz, 0.1V WITH 8mA DC BIAS
4. LEAKAGE INDUCTANCE : 0.5uH MAX @100kHz, 0.1V
5. DCR : 1400mΩ MAX.
6. INSERTION LOSS : -1.2dB MAX.(@0.5-1MHz)
-0.2-0.002*f^1.4dB MAX (@!1-125MHz)
7. RETURN LOSS : -16dB MIN.(@1-40MHz)
-10+20*log (f/80) dB MIN (@40.1-100MHz)
8. CROSS TALK : 1-100MHz : -30dB MIN.
9. CMRR : 1-100MHz : -30dB MIN.
10. OPERATING TEMPERATURE RANGE : 0°C~+70°C
11. IEEE802.3at COMPLIANTE PERFORMANCE
---720mA Current capability
12. STORAGE TEMPERATURE : -20°C to +125°C
13. RoHS COMPLIANT

								TITLE 10/100/1000 BASE-T PoE++ TRANSFORMER	
								DWG. NO. ATPL-526PR	
	RELEASE	09/03/2018	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY		SHEET 1 of 1
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE	P/N:	DRAW	
REVISIONS						09/03/18			SHIRLEY

3. Package :

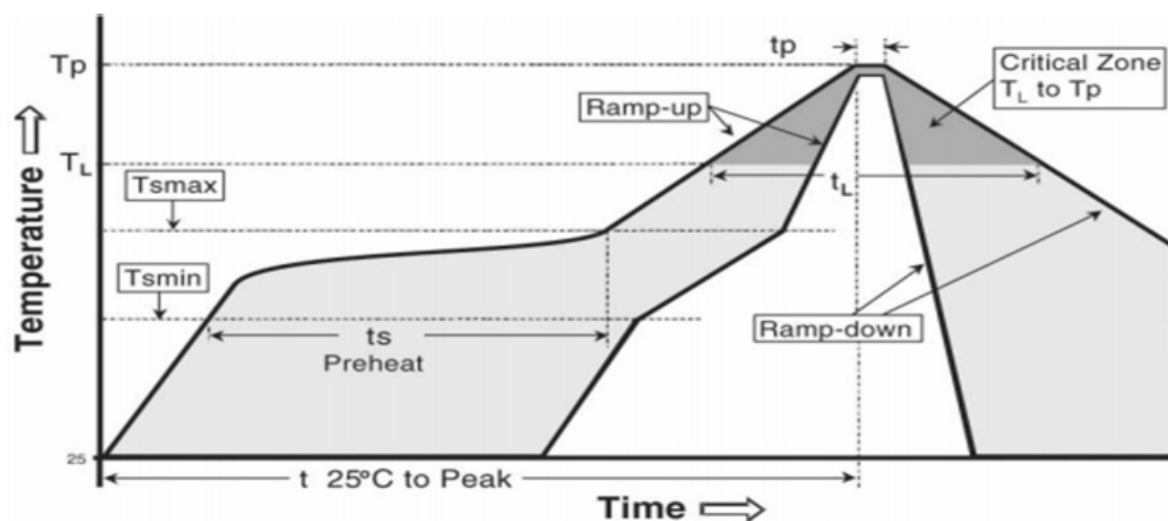


零件包裝符合EIA-481 standard(拉力 0.26N~1.3N)

Product	PCS/Tube	PCS/Box	Product No.	Weight(mg/pcs)
SMD 48 PIN Series	350	350x4=1400		2980

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max	3°C/second max
Preheat Temperature Min (Tsmmin)	100°C	150°C
Temperature Min (Tsmax)	150°C	200°C
Time (Tsmmin to Tsmax) (ts)	60-120seconds	60-180seconds
Time maintained above Temperature (TL)	183°C	217°C
Time (tL)	60-150seconds	60-150seconds
Peak Temperature (Tp)	225°C	260°C
Time within 5°C of actual Peak Temperature (Tp) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max